

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization International Bureau



(43) International Publication Date
29 December 2004 (29.12.2004)

PCT

(10) International Publication Number
WO 2004/114407 A1

(51) International Patent Classification⁷: H01L 25/065,
23/48

(21) International Application Number:
PCT/IB2004/002022

(22) International Filing Date: 16 June 2004 (16.06.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
03300035.7 20 June 2003 (20.06.2003) EP

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,

AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.

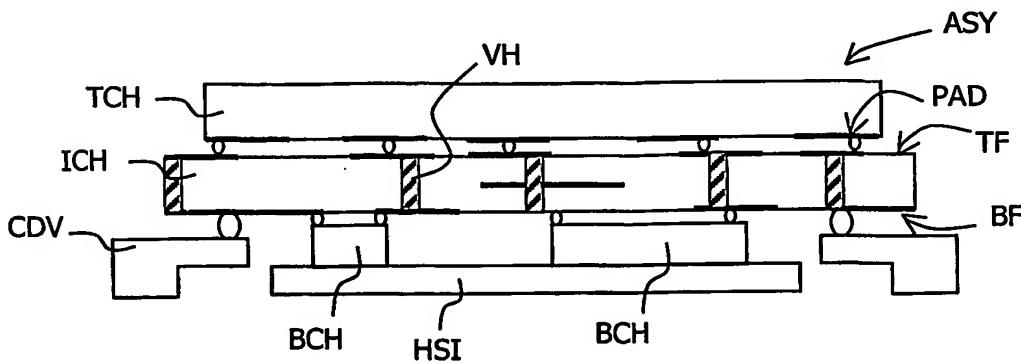
(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,
FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI,
SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,
GW, ML, MR, NE, SN, TD, TG).

Declaration under Rule 4.17:

— as to applicant's entitlement to apply for and be granted
a patent (Rule 4.17(ii)) for the following designations AE,
AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ,
CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE,
EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS,
JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA,
MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM,
PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ,
TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM,
ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, NA,

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(54) Title: OPTIMIZED MULTI-APPLICATION ASSEMBLY



(57) Abstract: The invention relates to a microelectronic chip assembly ASS comprising at least three microelectronic chip ICH, TCH, BCH stacked together and on which integrated devices are formed. At least one of the chip, called intermediate chip ICH, includes via holes VH running through said chip ICH and filled with conductive material is realized from a high-ohmic substrate on which are formed devices for the functioning of at least two other microelectronic chips, called top chip TCH and bottom chip BCH. Said top and bottom chips TCH and BCH are connected by flip chip bonding respectively on top face TF and bottom face BF of said intermediate chip ICH and said via holes VH are electrically connected to pads of said top and bottom chips TCH and BCH.

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SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)

Published:

— with international search report

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